

10/691,136

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|-----------------------------------------------------------------------------------------------------------------|----------------------------------------------|------------------|
| 1 | 71 | ((waveguide near8 (microns micrometers)) and @ad<20031021) and (solder near6 (ball bump column))) and substrate | USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/28 11:34 |
| 2 | 96 | ((conductive adj bump) near8 temperature) and solder and bond\$3 and @ad<20031021 | USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/28 11:36 |
| - | 2075 | (waveguide near8 (microns micrometers)) and @ad<20031021 | USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/27 19:06 |
| - | 181 | ((waveguide near8 (microns micrometers)) and @ad<20031021) and solder | USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/27 19:06 |
| - | 150 | ((waveguide near8 (microns micrometers)) and @ad<20031021) and solder) and substrate | USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/27 19:06 |
| - | 71 | ((waveguide near8 (microns micrometers)) and @ad<20031021) and (solder near6 (ball bump column)) | USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/27 19:07 |
| - | 71 | ((waveguide near8 (microns micrometers)) and @ad<20031021) and (solder near6 (ball bump column))) and substrate | USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/28 11:22 |